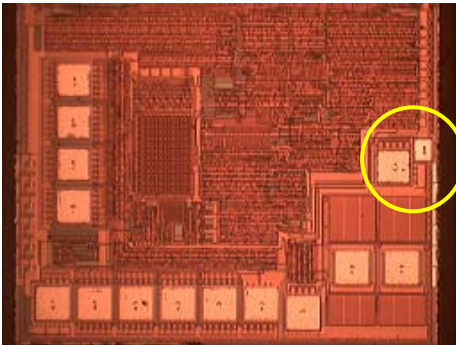


NY4A & NY4B Bonding Notice

Description:

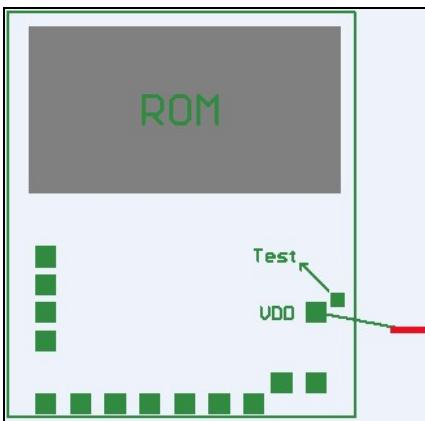
NY4A/NY4B Series IC will enter Test Mode when a high-level signal is input into the test pad. Whereas the test pad is quite close to VDD pad as IC is laid out, the bonding wire between VDD and golden finger may cross the Test Pad if the golden finger of PCB is arranged improperly. Thus IC will enter Test Mode, which leads to malfunction.

Below is NY4B Pad location figure. In the yellow circle, the larger pad is VDD Pad while the other is Test Pad.

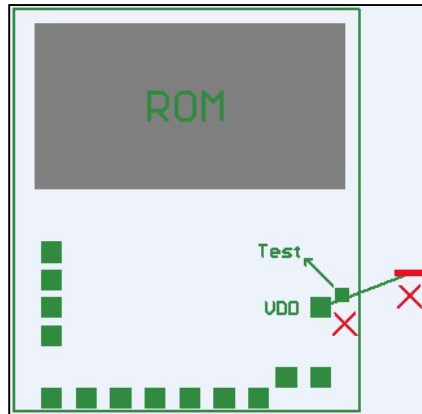


IC Bonding Notice:

In PCB Layout, the golden finger should be placed right lower IC VDD Pad, and therefore wire will not touch the Test Pad easily. If golden finger is facing VDD Pad or on the upper right of VDD Pad, the thread head may touch the Test Pad as IC bonding, and then enter Test Mode that leads to large current and no function. Diagram is shown below.



Correct golden finger arrangement



Incorrect golden finger arrangement

Please compare the photos of bad (left blow, with VDD bonding wire weeded out) and qualified (right blow) goods.

